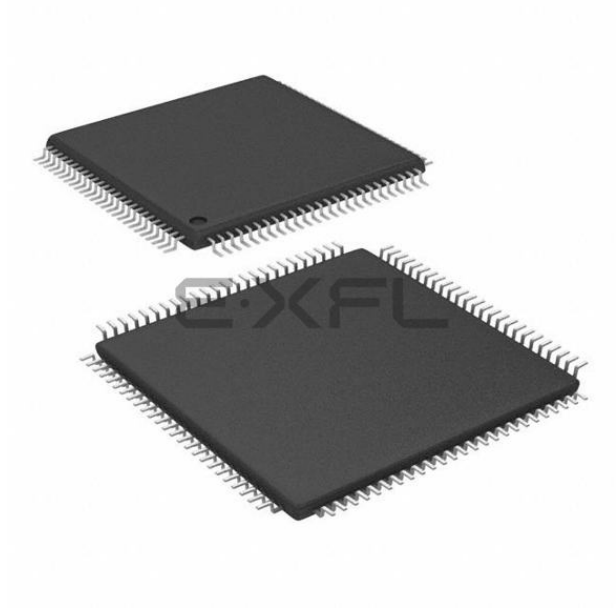

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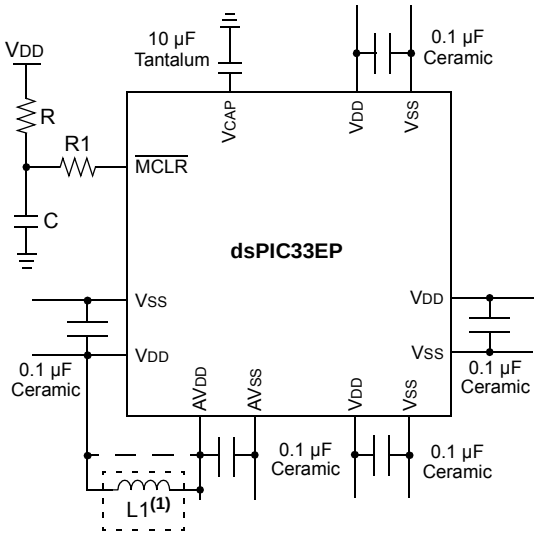
What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	-
Connectivity	CANbus, I²C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, I²S, Motor Control PWM, POR, PWM, WDT
Number of I/O	85
Program Memory Size	512KB (170K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	48K x 8
Voltage - Supply (Vcc/Vdd)	-
Data Converters	A/D 49x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 150°C (TA)
Mounting Type	Surface Mount
Package / Case	100-TQFP
Supplier Device Package	100-TQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep512gm710-h-pf

FIGURE 2-1: RECOMMENDED MINIMUM CONNECTION



Note 1: As an option, instead of a hard-wired connection, an inductor (L1) can be substituted between VDD and AVDD to improve ADC noise rejection. The inductor impedance should be less than 1Ω and the inductor capacity greater than 10 mA.

Where:

$$f = \frac{F_{CNV}}{2} \quad \text{(i.e., ADC Conversion Rate/2)}$$

$$f = \frac{1}{(2\pi\sqrt{LC})}$$

$$L = \left(\frac{1}{(2\pi f\sqrt{C})}\right)^2$$

2.2.1 TANK CAPACITORS

On boards with power traces running longer than six inches in length, it is suggested to use a tank capacitor for integrated circuits including DSCs to supply a local power source. The value of the tank capacitor should be determined based on the trace resistance that connects the power supply source to the device, and the maximum current drawn by the device in the application. In other words, select the tank capacitor so that it meets the acceptable voltage sag at the device. Typical values range from 4.7 µF to 47 µF.

2.3 CPU Logic Filter Capacitor Connection (VCAP)

A low-ESR (< 1 Ohms) capacitor is required on the VCAP pin, which is used to stabilize the voltage regulator output voltage. The VCAP pin must not be connected to VDD, and must have a capacitor greater than 4.7 µF (10 µF is recommended), 16V connected to ground. The type can be ceramic or tantalum. See **Section 33.0 "Electrical Characteristics"** for additional information.

The placement of this capacitor should be close to the VCAP pin. It is recommended that the trace length not exceeds one-quarter inch (6 mm). See **Section 30.3 "On-Chip Voltage Regulator"** for details.

2.4 Master Clear (MCLR) Pin

The MCLR pin provides two specific device functions:

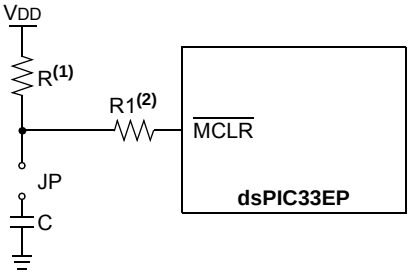
- Device Reset
- Device Programming and Debugging.

During device programming and debugging, the resistance and capacitance that can be added to the pin must be considered. Device programmers and debuggers drive the MCLR pin. Consequently, specific voltage levels (VIH and VIL) and fast signal transitions must not be adversely affected. Therefore, specific values of R and C will need to be adjusted based on the application and PCB requirements.

For example, as shown in Figure 2-2, it is recommended that the capacitor, C, be isolated from the MCLR pin during programming and debugging operations.

Place the components as shown in Figure 2-2 within one-quarter inch (6 mm) from the MCLR pin.

FIGURE 2-2: EXAMPLE OF MCLR PIN CONNECTIONS



Note 1: R ≤ 10 kΩ is recommended. A suggested starting value is 10 kΩ. Ensure that the MCLR pin VIH and VIL specifications are met.

2: R1 ≤ 470Ω will limit any current flowing into MCLR from the external capacitor, C, in the event of MCLR pin breakdown due to Electrostatic Discharge (ESD) or Electrical Overstress (EOS). Ensure that the MCLR pin VIH and VIL specifications are met.

2.5 ICSP Pins

The PGECx and PGEDx pins are used for ICSP and debugging purposes. It is recommended to keep the trace length between the ICSP connector and the ICSP pins on the device as short as possible. If the ICSP connector is expected to experience an ESD event, a series resistor is recommended, with the value in the range of a few tens of Ohms, not to exceed 100 Ohms.

Pull-up resistors, series diodes and capacitors on the PGECx and PGEDx pins are not recommended as they will interfere with the programmer/debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternatively, refer to the AC/DC characteristics and timing requirements information in the respective device Flash programming specification for information on capacitive loading limits and pin Voltage Input High (V_{IH}) and Voltage Input Low (V_{IL}) requirements.

Ensure that the "Communication Channel Select" (i.e., PGECx/PGEDx pins) programmed into the device matches the physical connections for the ICSP to MPLAB® PICkit™ 3, MPLAB ICD 3, or MPLAB REAL ICE™.

For more information on MPLAB ICD 2, ICD 3 and REAL ICE connection requirements, refer to the following documents that are available on the Microchip web site:

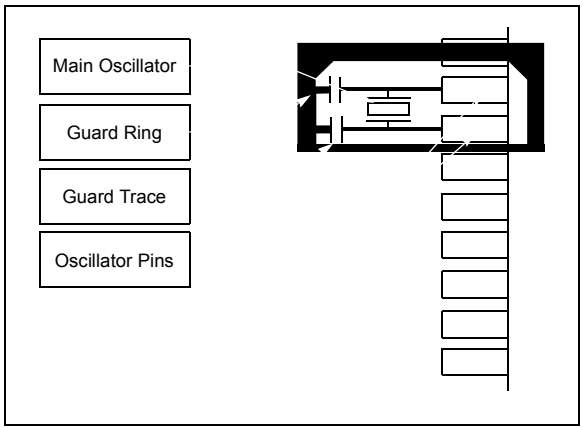
- *"Using MPLAB® ICD 3"* (poster) DS51765
- *"MPLAB® ICD 3 Design Advisory"* DS51764
- *"MPLAB® REAL ICE™ In-Circuit Emulator User's Guide"* DS51616
- *"Using MPLAB® REAL ICE™ In-Circuit Emulator"* (poster) DS51749

2.6 External Oscillator Pins

Many DSCs have options for at least two oscillators: a high-frequency primary oscillator and a low-frequency secondary oscillator. For details, see **Section 9.0 "Oscillator Configuration"** for details.

The oscillator circuit should be placed on the same side of the board as the device. Also, place the oscillator circuit close to the respective oscillator pins, not exceeding one-half inch (12 mm) distance between them. The load capacitors should be placed next to the oscillator itself, on the same side of the board. Use a grounded copper pour around the oscillator circuit to isolate them from surrounding circuits. The grounded copper pour should be routed directly to the MCU ground. Do not run any signal traces or power traces inside the ground pour. Also, if using a two-sided board, avoid any traces on the other side of the board where the crystal is placed. A suggested layout is shown in Figure 2-3.

FIGURE 2-3: SUGGESTED PLACEMENT OF THE OSCILLATOR CIRCUIT



REGISTER 3-1: SR: CPU STATUS REGISTER (CONTINUED)

bit 7-5 **IPL<2:0>:** CPU Interrupt Priority Level Status bits(1,2)

111 = CPU Interrupt Priority Level is 7 (15); user interrupts are disabled
110 = CPU Interrupt Priority Level is 6 (14)
101 = CPU Interrupt Priority Level is 5 (13)
100 = CPU Interrupt Priority Level is 4 (12)
011 = CPU Interrupt Priority Level is 3 (11)
010 = CPU Interrupt Priority Level is 2 (10)
001 = CPU Interrupt Priority Level is 1 (9)
000 = CPU Interrupt Priority Level is 0 (8)

bit 4 **RA:** REPEAT Loop Active bit

1 = REPEAT loop is in progress
0 = REPEAT loop is not in progress

bit 3 **N:** MCU ALU Negative bit

1 = Result was negative
0 = Result was non-negative (zero or positive)

bit 2 **OV:** MCU ALU Overflow bit

This bit is used for signed arithmetic (2's complement). It indicates an overflow of the magnitude that causes the sign bit to change state.
1 = Overflow occurred for signed arithmetic (in this arithmetic operation)
0 = No overflow occurred

bit 1 **Z:** MCU ALU Zero bit

1 = An operation that affects the Z bit has set it at some time in the past
0 = The most recent operation that affects the Z bit has cleared it (i.e., a non-zero result)

bit 0 **C:** MCU ALU Carry/$\overline{\text{Borrow}}$ bit

1 = A carry-out from the Most Significant bit (MSb) of the result occurred
0 = No carry-out from the Most Significant bit of the result occurred

Note 1: The IPL<2:0> bits are concatenated with the IPL<3> bit (CORCON<3>) to form the CPU Interrupt Priority Level. The value in parentheses indicates the IPL, if IPL<3> = 1. User interrupts are disabled when IPL<3> = 1.

2: The IPL<2:0> Status bits are read-only when the NSTDIS bit (INTCON1<15>) = 1.

3: A data write to the SR register can modify the SA and SB bits by either a data write to SA and SB or by clearing the SAB bit. To avoid a possible SA or SB bit write race condition, the SA and SB bits should not be modified using bit operations.

TABLE 4-25: CAN1 REGISTER MAP WHEN WIN (C1CTRL<0>) = 1 FOR dsPIC33EPXXXGM60X/7XX DEVICES(1) (CONTINUED)

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
C1RXF11SID	046C	SID10	SID9	SID8	SID7	SID6	SID5	SID4	SID3	SID2	SID1	SID0	—	EXIDE	—	EID17	EID16	xxxx
C1RXF11EID	046E	EID<15:0>																xxxx
C1RXF12SID	0470	SID10	SID9	SID8	SID7	SID6	SID5	SID4	SID3	SID2	SID1	SID0	—	EXIDE	—	EID17	EID16	xxxx
C1RXF12EID	0472	EID<15:0>																xxxx
C1RXF13SID	0474	SID10	SID9	SID8	SID7	SID6	SID5	SID4	SID3	SID2	SID1	SID0	—	EXIDE	—	EID17	EID16	xxxx
C1RXF13EID	0476	EID<15:0>																xxxx
C1RXF14SID	0478	SID10	SID9	SID8	SID7	SID6	SID5	SID4	SID3	SID2	SID1	SID0	—	EXIDE	—	EID17	EID16	xxxx
C1RXF14EID	047A	EID<15:0>																xxxx
C1RXF15SID	047C	SID10	SID9	SID8	SID7	SID6	SID5	SID4	SID3	SID2	SID1	SID0	—	EXIDE	—	EID17	EID16	xxxx
C1RXF15EID	047E	EID<15:0>																xxxx

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.
Note 1: These registers are not present on dsPIC33EPXXXGM3XX devices.

TABLE 4-26: CAN2 REGISTER MAP WHEN WIN (C1CTRL<0>) = 0 OR 1 FOR dsPIC33EPXXXGM60X/7XX DEVICES(1)

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
C2CTRL1	0500	—	—	CSIDL	ABAT	CANCKS	REQOP2	REQOP1	REQOP0	OPMODE2	OPMODE1	OPMODE0	—	CANCAP	—	—	WIN	0480
C2CTRL2	0502	—	—	—	—	—	—	—	—	—	—	—	DNCNT<4:0>					0000
C2VEC	0504	—	—	—	FILHIT4	FILHIT3	FILHIT2	FILHIT1	FILHIT0	—	ICODE6	ICODE5	ICODE4	ICODE3	ICODE2	ICODE1	ICODE0	0040
C2FCTRL	0506	DMABS2	DMABS1	DMABS0	—	—	—	—	—	—	—	—	FSA4	FSA3	FSA2	FSA1	FSA0	0000
C2FIFO	0508	—	—	FBP5	FBP4	FBP3	FBP2	FBP1	FBP0	—	—	FNRB5	FNRB4	FNRB3	FNRB2	FNRB1	FNRB0	0000
C2INTF	050A	—	—	TXBO	TXBP	RXBP	TXWAR	RXWAR	EWARN	IVRIF	WAKIF	ERRIF	—	FIFOIF	RBOVIF	RBIF	TBIF	0000
C2INTE	050C	—	—	—	—	—	—	—	—	IVRIE	WAKIE	ERRIE	—	FIFOIE	RBOVIE	RBIE	TBIE	0000
C2EC	050E	TERRCNT7	TERRCNT6	TERRCNT5	TERRCNT4	TERRCNT3	TERRCNT2	TERRCNT1	TERRCNT0	RERRCNT7	RERRCNT6	RERRCNT5	RERRCNT4	RERRCNT3	RERRCNT2	RERRCNT1	RERRCNT0	0000
C2CFG1	0510	—	—	—	—	—	—	—	—	SJW1	SJW0	BRP5	BRP4	BRP3	BRP2	BRP1	BRP0	0000
C2CFG2	0512	—	WAKFIL	—	—	—	SEG2PH2	SEG2PH1	SEG2PH0	SEG2PHTS	SAM	SEG1PH2	SEG1PH1	SEG1PH0	PRSEG2	PRSEG1	PRSEG0	0000
C2FEN1	0514	FLTEN<15:0>																FFFF
C2FMSKSEL1	0518	F7MSK1	F7MSK0	F6MSK1	F6MSK0	F5MSK1	F5MSK0	F4MSK1	F4MSK0	F3MSK1	F3MSK0	F2MSK1	F2MSK0	F1MSK1	F1MSK0	F0MSK1	F0MSK0	0000
C2FMSKSEL2	051A	F15MSK1	F15MSK0	F14MSK1	F14MSK0	F13MSK1	F13MSK0	F12MSK1	F12MSK0	F11MSK1	F11MSK0	F10MSK1	F10MSK0	F9MSK1	F9MSK0	F8MSK1	F8MSK0	0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.
Note 1: These registers are not present on dsPIC33EPXXXGM3XX devices.

8.0 DIRECT MEMORY ACCESS (DMA)

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGM3XX/6XX/7XX family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the *"dsPIC33/PIC24 Family Reference Manual"*, **"Direct Memory Access (DMA)"** (DS70348), which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The DMA Controller transfers data between Peripheral Data registers and Data Space SRAM

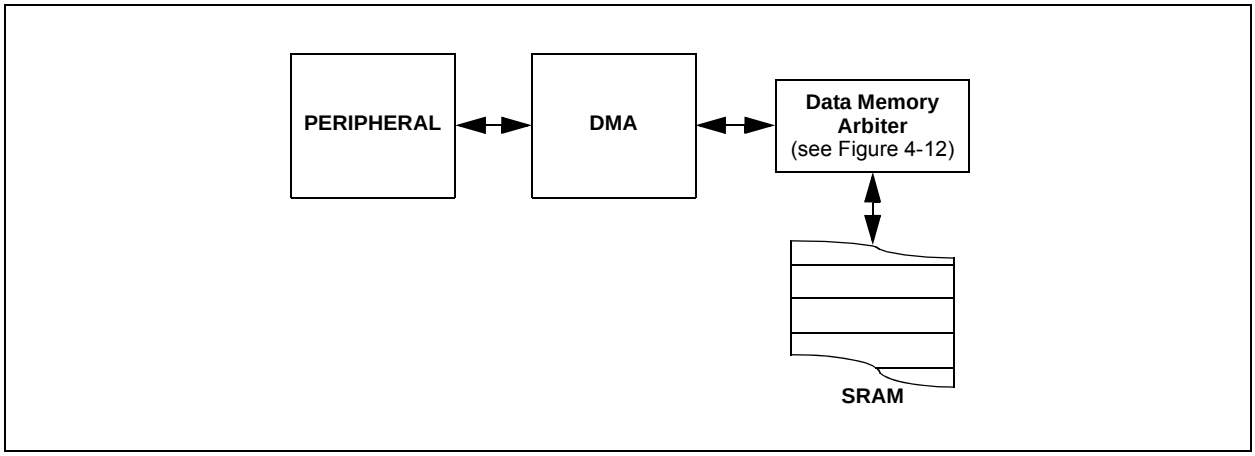
In addition, DMA can access the entire data memory space. The data memory bus arbiter is utilized when either the CPU or DMA attempts to access SRAM, resulting in potential DMA or CPU stalls.

The DMA Controller supports 4 independent channels. Each channel can be configured for transfers to or from selected peripherals. The peripherals supported by the DMA Controller include:

- CAN
- Analog-to-Digital Converter (ADC)
- Serial Peripheral Interface (SPI)
- UART
- Input Capture
- Output Compare
- DCI
- PMP
- Timers

Refer to Table 8-1 for a complete list of supported peripherals.

FIGURE 8-1: PERIPHERAL TO DMA CONTROLLER



REGISTER 10-4: PMD4: PERIPHERAL MODULE DISABLE CONTROL REGISTER 4

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	R/W-0	U-0	R/W-0	R/W-0	U-0	U-0
—	—	U4MD	—	REFOMD	CTMUMD	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-6 **Unimplemented:** Read as ‘0’

bit 5 **U4MD:** UART4 Module Disable bit
1 = UART4 module is disabled
0 = UART4 module is enabled

bit 4 **Unimplemented:** Read as ‘0’

bit 3 **REFOMD:** Reference Clock Module Disable bit
1 = Reference clock module is disabled
0 = Reference clock module is enabled

bit 2 **CTMUMD:** CTMU Module Disable bit
1 = CTMU module is disabled
0 = CTMU module is enabled

bit 1-0 **Unimplemented:** Read as ‘0’

REGISTER 10-5: PMD6: PERIPHERAL MODULE DISABLE CONTROL REGISTER 6

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	PWM6MD	PWM5MD	PWM4MD	PWM3MD	PWM2MD	PWM1MD
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0
—	—	—	—	—	—	—	SPI3MD
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as ‘0’

bit 13-8 **PWM6MD:PWM1MD:** PWMx (x = 1-6) Module Disable bit
1 = PWMx module is disabled
0 = PWMx module is enabled

bit 7-1 **Unimplemented:** Read as ‘0’

bit 0 **SPI3MD:** SPI3 Module Disable bit
1 = SPI3 module is disabled
0 = SPI3 module is enabled

11.5 High-Voltage Detect

The dsPIC33EPXXXGM3XX/6XX/7XX devices contain High-Voltage Detection (HVD) which monitors the VCAP voltage. The HVD is used to monitor the VCAP supply voltage to ensure that an external connection does not raise the value above a safe level (~2.4V). If high core voltage is detected, all I/Os are disabled and put in a tri-state condition. The device remains in this I/O tri-state condition as long as the high-voltage condition is present.

11.6 I/O Helpful Tips

1. In some cases, certain pins, as defined in Table 33-10 under “Injection Current”, have internal protection diodes to VDD and VSS. The term, “Injection Current”, is also referred to as “Clamp Current”. On designated pins with sufficient external current-limiting precautions by the user, I/O pin input voltages are allowed to be greater or less than the data sheet absolute maximum ratings, with respect to the VSS and VDD supplies. Note that when the user application forward biases either of the high or low side internal input clamp diodes, that the resulting current being injected into the device that is clamped internally by the VDD and VSS power rails, may affect the ADC accuracy by four to six counts.
2. I/O pins that are shared with any analog input pin (i.e., ANx) are always analog pins by default after any Reset. Consequently, configuring a pin as an analog input pin automatically disables the digital input pin buffer and any attempt to read the digital input level by reading PORTx or LATx will always return a ‘0’, regardless of the digital logic level on the pin. To use a pin as a digital I/O pin on a shared ANx pin, the user application needs to configure the Analog Pin Configuration registers in the I/O ports module (i.e., ANSELx) by setting the appropriate bit that corresponds to that I/O port pin to a ‘0’.

Note:	Although it is not possible to use a digital input pin when its analog function is enabled, it is possible to use the digital I/O output function, TRISx = 0x0, while the analog function is also enabled. However, this is not recommended, particularly if the analog input is connected to an external analog voltage source, which would create signal contention between the analog signal and the output pin driver.

3. Most I/O pins have multiple functions. Referring to the device pin diagrams in this data sheet, the priorities of the functions allocated to any pins are indicated by reading the pin name from left-to-right. The left most function name takes precedence over any function to its right in the naming convention. For example: AN16/T2CK/T7CK/RC1. This indicates that AN16 is the highest priority in this example and will supersede all other functions to its right in the list. Those other functions to its right, even if enabled, would not work as long as any other function to its left was enabled. This rule applies to all of the functions listed for a given pin.
4. Each pin has an internal weak pull-up resistor and pull-down resistor that can be configured using the CNPUx and CNPDx registers, respectively. These resistors eliminate the need for external resistors in certain applications. The internal pull-up is up to ~(VDD – 0.8), not VDD. This value is still above the minimum VIH of CMOS and TTL devices.
5. When driving LEDs directly, the I/O pin can source or sink more current than what is specified in the VOH/IOH and VOL/IOL DC characteristic specifications. The respective IOH and IOL current rating only applies to maintaining the corresponding output at or above the VOH and at or below the VOL levels. However, for LEDs, unlike digital inputs of an externally connected device, they are not governed by the same minimum VIH/VIL levels. An I/O pin output can safely sink or source any current less than that listed in the absolute maximum rating section of this data sheet. For example:

   VOH = 2.4V @ IOH = -8 mA and VDD = 3.3V

   The maximum output current sourced by any 8 mA I/O pin = 12 mA.

   LED source current < 12 mA is technically permitted. Refer to the VOH/IOH graphs in **Section 33.0 “Electrical Characteristics”** for additional information.

REGISTER 14-2: ICxCON2: INPUT CAPTURE x CONTROL REGISTER 2 (CONTINUED)

bit 4-0 **SYNCSEL<4:0>:** Input Source Select for Synchronization and Trigger Operation bits(4)

11111 = Capture timer is unsynchronized
11110 = Capture timer is unsynchronized
11101 = Capture timer is unsynchronized
11100 = CTMU trigger is the source for the capture timer synchronization
11011 = ADC1 interrupt is the source for the capture timer synchronization(5)
11010 = Analog Comparator 3 is the source for the capture timer synchronization(5)
11001 = Analog Comparator 2 is the source for the capture timer synchronization(5)
11000 = Analog Comparator 1 is the source for the capture timer synchronization(5)
10111 = Input Capture 8 interrupt is the source for the capture timer synchronization
10110 = Input Capture 7 interrupt is the source for the capture timer synchronization
10101 = Input Capture 6 interrupt is the source for the capture timer synchronization
10100 = Input Capture 5 interrupt is the source for the capture timer synchronization
10011 = Input Capture 4 interrupt is the source for the capture timer synchronization
10010 = Input Capture 3 interrupt is the source for the capture timer synchronization
10001 = Input Capture 2 interrupt is the source for the capture timer synchronization
10000 = Input Capture 1 interrupt is the source for the capture timer synchronization
01111 = GP Timer5 is the source for the capture timer synchronization
01110 = GP Timer4 is the source for the capture timer synchronization
01101 = GP Timer3 is the source for the capture timer synchronization
01100 = GP Timer2 is the source for the capture timer synchronization
01011 = GP Timer1 is the source for the capture timer synchronization
01010 = PTGx trigger is the source for the capture timer synchronization(6)
01001 = Capture timer is unsynchronized
01000 = Output Compare 8 is the source for the capture timer synchronization
00111 = Output Compare 7 is the source for the capture timer synchronization
00110 = Output Compare 6 is the source for the capture timer synchronization
00101 = Output Compare 5 is the source for the capture timer synchronization
00100 = Output Compare 4 is the source for the capture timer synchronization
00011 = Output Compare 3 is the source for the capture timer synchronization
00010 = Output Compare 2 is the source for the capture timer synchronization
00001 = Output Compare 1 is the source for the capture timer synchronization
00000 = Capture timer is unsynchronized

Note 1: The IC32 bit in both the Odd and Even ICx must be set to enable Cascade mode.

2: The input source is selected by the SYNCSEL<4:0> bits of the ICxCON2 register.

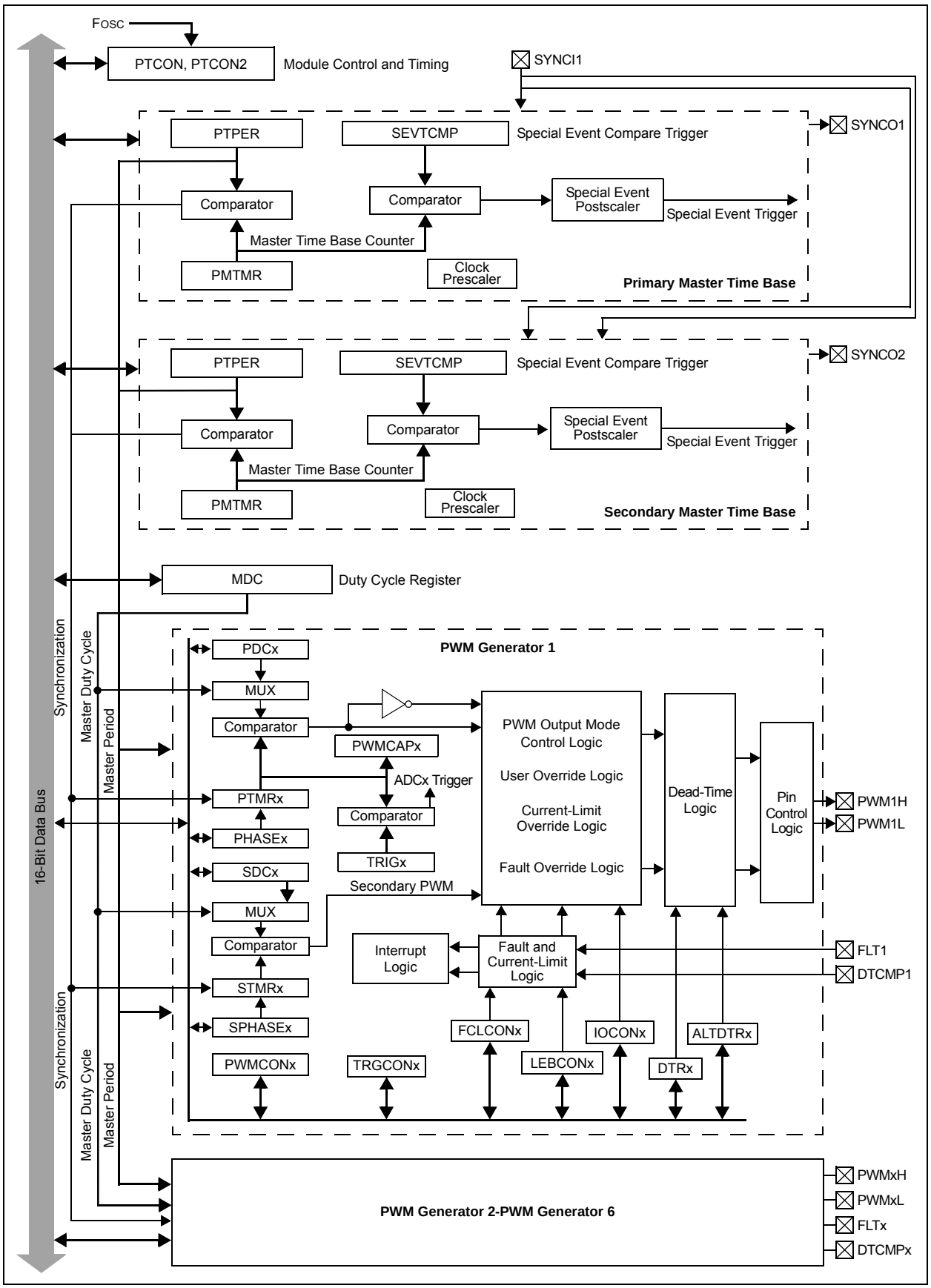
3: This bit is set by the selected input source (selected by SYNCSEL<4:0> bits); it can be read, set and cleared in software.

4: Do not use the ICx module as its own Sync or Trigger source.

5: This option should only be selected as a trigger source and not as a synchronization source.

6: Each Input Capture x module (ICx) has one PTG input source. See **Section 25.0 “Peripheral Trigger Generator (PTG) Module”** for more information.
PTGO8 = IC1, IC5
PTGO9 = IC2, IC6
PTGO10 = IC3, IC7
PTGO11 = IC4, IC8

FIGURE 16-2: HIGH-SPEED PWMx MODULE REGISTER INTERCONNECTION DIAGRAM



NOTES:

REGISTER 22-3: CTMUICON: CTMU CURRENT CONTROL REGISTER(3)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ITRIM5	ITRIM4	ITRIM3	ITRIM2	ITRIM1	ITRIM0	IRNG1	IRNG0
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-10 **ITRIM<5:0>:** Current Source Trim bits
011111 = Maximum positive change from nominal current + 62%
011110 = Maximum positive change from nominal current + 60%
•
•
•
000010 = Minimum positive change from nominal current + 4%
000001 = Minimum positive change from nominal current + 2%
000000 = Nominal current output specified by IRNG<1:0>
111111 = Minimum negative change from nominal current – 2%
111110 = Minimum negative change from nominal current – 4%
•
•
•
100010 = Maximum negative change from nominal current – 60%
100001 = Maximum negative change from nominal current – 62%

bit 9-8 **IRNG<1:0>:** Current Source Range Select bits
11 = 100 × Base Current(2)
10 = 10 × Base Current(2)
01 = Base Current Level(2)
00 = 1000 × Base Current(1,2)

bit 7-0 **Unimplemented:** Read as '0'

Note 1: This current range is not available for use with the internal temperature measurement diode.

2: Refer to the CTMU Current Source Specifications (Table 33-55) in **Section 33.0 "Electrical Characteristics"** for the current range selection values.

3: Current sources are not generated when 12-Bit ADC mode is chosen. Current sources are active only when 10-Bit ADC mode is chosen.

REGISTER 23-2: ADxCON2: ADCx CONTROL REGISTER 2 (CONTINUED)

bit 6-2 **SMPI<4:0>:** Increment Rate bits

When ADDMAEN = 0:

x1111 = Generates interrupt after completion of every 16th sample/conversion operation
x1110 = Generates interrupt after completion of every 15th sample/conversion operation
•
•
•
x0001 = Generates interrupt after completion of every 2nd sample/conversion operation
x0000 = Generates interrupt after completion of every sample/conversion operation

When ADDMAEN = 1:

11111 = Increments the DMA address after completion of every 32nd sample/conversion operation
11110 = Increments the DMA address after completion of every 31st sample/conversion operation
•
•
•
00001 = Increments the DMA address after completion of every 2nd sample/conversion operation
00000 = Increments the DMA address after completion of every sample/conversion operation

bit 1 **BUFM:** Buffer Fill Mode Select bit

1 = Starts buffer filling the first half of the buffer on the first interrupt and the second half of the buffer on the next interrupt
0 = Always starts filling the buffer from the Start address

bit 0 **ALTS:** Alternate Input Sample Mode Select bit

1 = Uses channel input selects for Sample MUXA on the first sample and Sample MUXB on the next sample
0 = Always uses channel input selects for Sample MUXA

Note 1: The '001', '010' and '011' bit combinations for VCFG<2:0> are not applicable on ADC2.

2: ADC2 does not support external VREF± inputs.

REGISTER 24-3: DCICON3: DCI CONTROL REGISTER 3

r-0	r-0	r-0	r-0	R/W-0	R/W-0	R/W-0	R/W-0
r	r	r	r	BCG<11:8>			
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
BCG<7:0>							
bit 7							bit 0

Legend:	r = Reserved bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-12 **Reserved:** Read as '0'

bit 11-0 **BCG<11:0>:** DCI Bit Clock Generator Control bits

NOTES:

NOTES:

32.2 MPLAB XC Compilers

The MPLAB XC Compilers are complete ANSI C compilers for all of Microchip's 8, 16 and 32-bit MCU and DSC devices. These compilers provide powerful integration capabilities, superior code optimization and ease of use. MPLAB XC Compilers run on Windows, Linux or MAC OS X.

For easy source level debugging, the compilers provide debug information that is optimized to the MPLAB X IDE.

The free MPLAB XC Compiler editions support all devices and commands, with no time or memory restrictions, and offer sufficient code optimization for most applications.

MPLAB XC Compilers include an assembler, linker and utilities. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. MPLAB XC Compiler uses the assembler to produce its object file. Notable features of the assembler include:

- Support for the entire device instruction set
- Support for fixed-point and floating-point data
- Command-line interface
- Rich directive set
- Flexible macro language
- MPLAB X IDE compatibility

32.3 MPASM Assembler

The MPASM Assembler is a full-featured, universal macro assembler for PIC10/12/16/18 MCUs.

The MPASM Assembler generates relocatable object files for the MPLINK Object Linker, Intel® standard HEX files, MAP files to detail memory usage and symbol reference, absolute LST files that contain source lines and generated machine code, and COFF files for debugging.

The MPASM Assembler features include:

- Integration into MPLAB X IDE projects
- User-defined macros to streamline assembly code
- Conditional assembly for multipurpose source files
- Directives that allow complete control over the assembly process

32.4 MPLINK Object Linker/ MPLIB Object Librarian

The MPLINK Object Linker combines relocatable objects created by the MPASM Assembler. It can link relocatable objects from precompiled libraries, using directives from a linker script.

The MPLIB Object Librarian manages the creation and modification of library files of precompiled code. When a routine from a library is called from a source file, only the modules that contain that routine will be linked in with the application. This allows large libraries to be used efficiently in many different applications.

The object linker/library features include:

- Efficient linking of single libraries instead of many smaller files
- Enhanced code maintainability by grouping related modules together
- Flexible creation of libraries with easy module listing, replacement, deletion and extraction

32.5 MPLAB Assembler, Linker and Librarian for Various Device Families

MPLAB Assembler produces relocatable machine code from symbolic assembly language for PIC24, PIC32 and dsPIC DSC devices. MPLAB XC Compiler uses the assembler to produce its object file. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. Notable features of the assembler include:

- Support for the entire device instruction set
- Support for fixed-point and floating-point data
- Command-line interface
- Rich directive set
- Flexible macro language
- MPLAB X IDE compatibility

FIGURE 33-19: SPI2 AND SPI3 SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 0, SMP = 0) TIMING CHARACTERISTICS

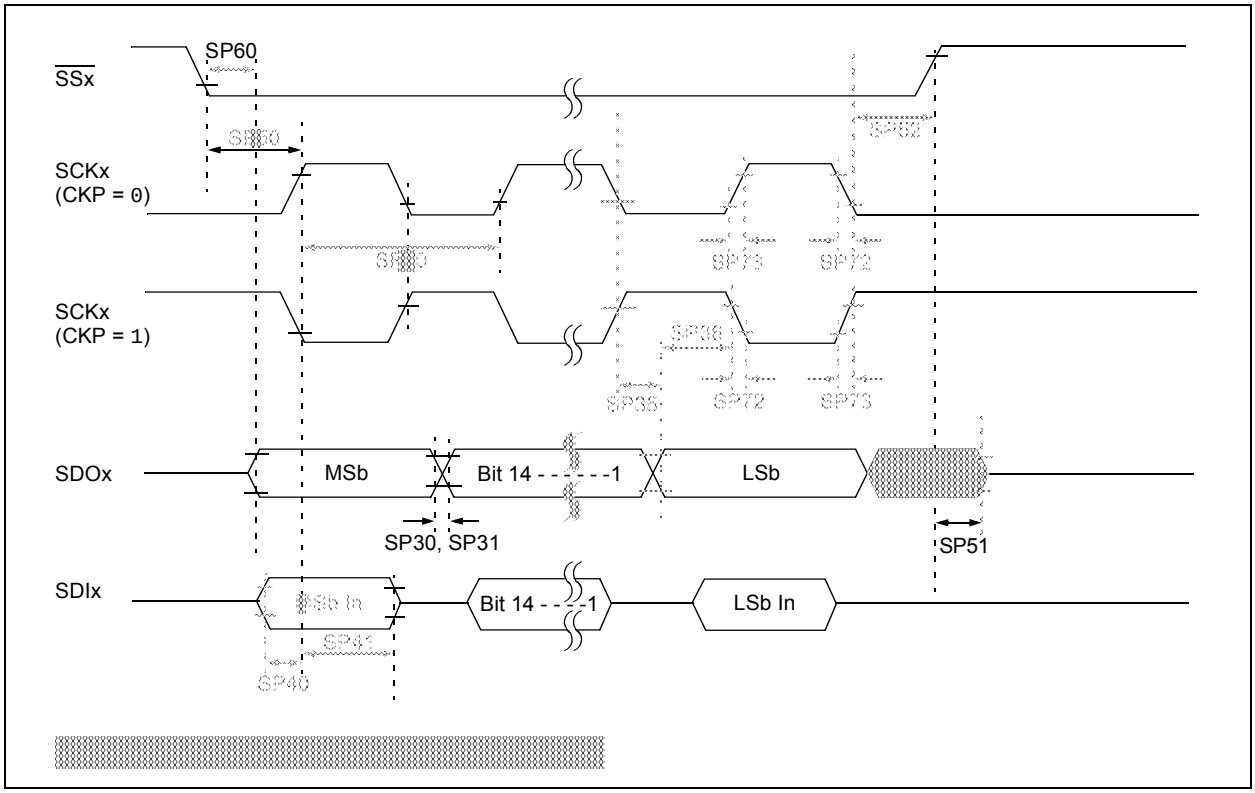


TABLE 33-49: I2Cx BUS DATA TIMING REQUIREMENTS (SLAVE MODE)

AC CHARACTERISTICS				Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Param. No.	**Symbol**	**Characteristic(3)**		**Min.**	**Max.**	**Units**	**Conditions**
IS10	TLO:SCL	Clock Low Time	100 kHz mode	4.7	—	µs	
			400 kHz mode	1.3	—	µs	
			1 MHz mode(1)	0.5	—	µs	
IS11	THI:SCL	Clock High Time	100 kHz mode	4.0	—	µs	Device must operate at a minimum of 1.5 MHz
			400 kHz mode	0.6	—	µs	Device must operate at a minimum of 10 MHz
			1 MHz mode(1)	0.5	—	µs	
IS20	TF:SCL	SDAx and SCLx Fall Time	100 kHz mode	—	300	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode(1)	—	100	ns	
IS21	TR:SCL	SDAx and SCLx Rise Time	100 kHz mode	—	1000	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode(1)	—	300	ns	
IS25	TSU:DAT	Data Input Setup Time	100 kHz mode	250	—	ns	
			400 kHz mode	100	—	ns	
			1 MHz mode(1)	100	—	ns	
IS26	THD:DAT	Data Input Hold Time	100 kHz mode	0	—	µs	
			400 kHz mode	0	0.9	µs	
			1 MHz mode(1)	0	0.3	µs	
IS30	TSU:STA	Start Condition Setup Time	100 kHz mode	4.7	—	µs	Only relevant for Repeated Start condition
			400 kHz mode	0.6	—	µs	
			1 MHz mode(1)	0.25	—	µs	
IS31	THD:STA	Start Condition Hold Time	100 kHz mode	4.0	—	µs	After this period, the first clock pulse is generated
			400 kHz mode	0.6	—	µs	
			1 MHz mode(1)	0.25	—	µs	
IS33	TSU:STO	Stop Condition Setup Time	100 kHz mode	4.7	—	µs	
			400 kHz mode	0.6	—	µs	
			1 MHz mode(1)	0.6	—	µs	
IS34	THD:STO	Stop Condition Hold Time	100 kHz mode	4	—	µs	
			400 kHz mode	0.6	—	µs	
			1 MHz mode(1)	0.25		µs	
IS40	TAA:SCL	Output Valid From Clock	100 kHz mode	0	3500	ns	
			400 kHz mode	0	1000	ns	
			1 MHz mode(1)	0	350	ns	
IS45	TBF:SDA	Bus Free Time	100 kHz mode	4.7	—	µs	Time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	µs	
			1 MHz mode(1)	0.5	—	µs	
IS50	CB	Bus Capacitive Loading		—	400	pF	
IS51	TPGD	Pulse Gobbler Delay		65	390	ns	**(Note 2)**

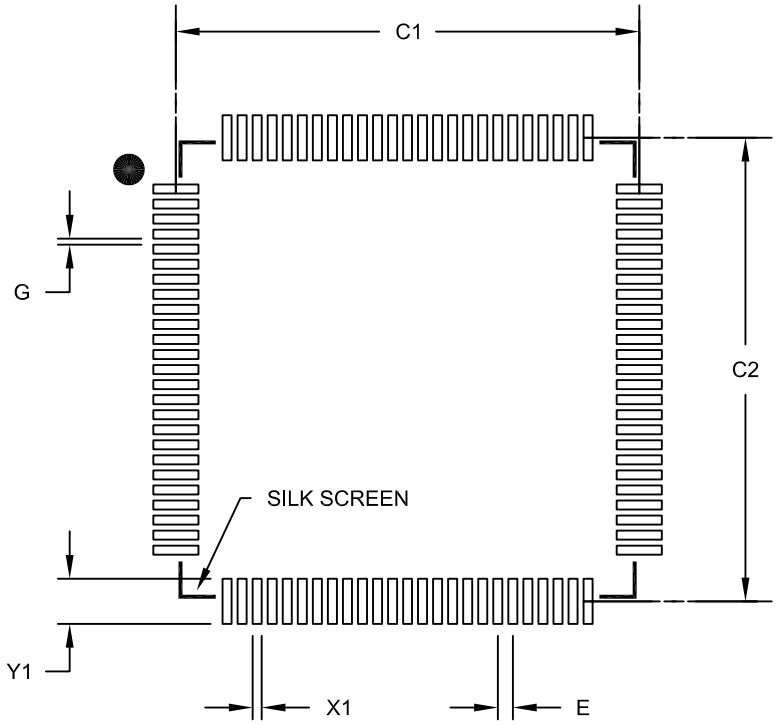
Note 1: Maximum pin capacitance = 10 pF for all I2Cx pins (for 1 MHz mode only).

2: The Typical value for this parameter is 130 ns.

3: These parameters are characterized, but not tested in manufacturing.

100-Lead Plastic Thin Quad Flatpack (PF) - 14x14x1 mm Body 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.50 BSC	
Contact Pad Spacing	C1		15.40	
Contact Pad Spacing	C2		15.40	
Contact Pad Width (X100)	X1			0.30
Contact Pad Length (X100)	Y1			1.50
Distance Between Pads	G	0.20		

Notes:

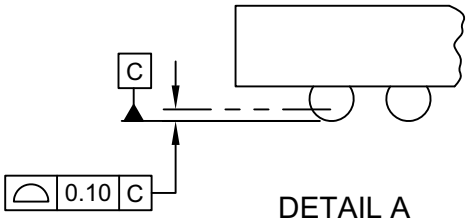
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

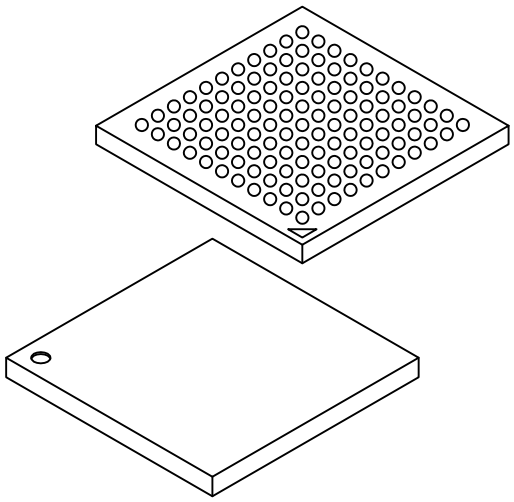
Microchip Technology Drawing No. C04-2110B

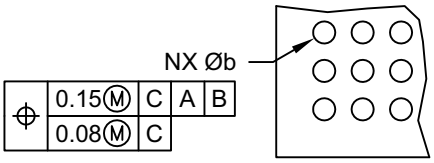
121-Ball Plastic Thin Profile Fine Pitch Ball Grid Array (BG) - 10x10x1.10 mm Body [TFBGA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



DETAIL A





DETAIL B

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Contacts	N		121	
Contact Pitch	e		0.80 BSC	
Overall Height	A	1.00	1.10	1.20
Ball Height	A1	0.25	0.30	0.35
Overall Width	E		10.00 BSC	
Array Width	E1		8.00 BSC	
Overall Length	D		10.00 BSC	
Array Length	D1		8.00 BSC	
Contact Diameter	b	0.35	0.40	0.45

Notes:

1. Ball A1 visual index feature may vary, but must be located within the hatched area.
2. Dimensioning and tolerancing per ASME Y14.5M.
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
   REF: Reference Dimension, usually without tolerance, for information purposes only.
3. The outer rows and colums of balls are located with respect to datums A and B.
4. Ball interface to package body: 0.37mm nominal diameter.

Microchip Technology Drawing C04-148 Rev F Sheet 2 of 2